ASEDCIATION CONNECTING ELECTRONICS INDUSTRIES® International and	<b>position De</b> IPC, Bannockt Pan-American co	<b>claration</b> ourn, Illinois. <i>A</i> opyright conve	All rights reserved untions.	under both	This docume level parts, t	ent is a declaration en declaration	on of the substan	ces within the ma wer level materia	nufacturer list lls for which t	ed item. Note: i he manufacturer	f the item is an as has engineering	ssembly with low responsibility.	
	IPC Web Site for Information on IPC-1752 Standard         Form Typ           http://www.ipc.org/IPC-175x         Distribute				<ul> <li>Declaration Class *</li> <li>Class 6 - RoHS Yes/No, Homogeneous Materia</li> </ul>				s Materials an	ials and Mfg Information			
upplier Information													
ompany name*	Company unique ID			1	Unique ID Authority				Response Date*				
nsemi									2025-06-03				
Contact Name			Title - Contact			Phone - Contact*				Email - Contact*			
Product-Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorized Representative*	Title - Representative			]	Phone - Representative*			Ema	Email - Representative*				
Product-Env-Stewards Pro			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Requester Item Number Mfr Iter		n Number Mfr Item Name				Effective Date	Version	Manufacturing Site CP8		Weight*	UOM	Unit Type	
	KSE130	KSE13003H1ASTU NPN/1.		PN/1.5A/700V TO-126		2025-06-03				837.057	mg	Each	
Ianufacturing Proccess Inforn	nation					•							
Terminal Plating / Grid Array	rminal Plating / Grid Array Material Terminal Bas		Alloy	J-STD-020 MSL Rati		Peak Process Body Temperature M		ature Max Time	at Peak Temp	erature Numb	er of Reflow Cy	cles	
Matte Tin (Sn) - annealed		CU Alloy NA			0 C 30		30	S	econds 3				
omments													
or more information regarding mater	al composition	please refer to	o page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et						
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 4 - Item(	s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature	astislav Drska	Le								

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.38	mg	Supplier	Silicon (Si)	7440-21-3		0.38	mg
Die Attach	0.229	mg	Supplier	Silver (Ag)	7440-22-4		0.0034	mg
			А	Lead (Pb)	7439-92-1	7a	0.2141	mg
			Supplier	Tin (Sn)	7440-31-5		0.0115	mg
Lead Frame	362.5	mg	Supplier	Iron (Fe)	7439-89-6		0.3625	mg
			Supplier	Copper (Cu)	7440-50-8		362.0287	mg
			Supplier	Phosphorus (P)	7723-14-0		0.1087	mg
Mold Compound-Black	461.72	mg	Supplier	2,6-dibromo-4-[1-(3-bromo-4- hydroxyphenyl)-1-methylethyl]phenol	6386-73-8		1.3852	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		4.6172	mg
			Supplier	Carbon Black (C)	1333-86-4		5.5406	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		78.4924	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		55.4064	mg
			Supplier	Silica (SiO2)	14464-46-1		2.3086	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		36.9376	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		277.032	mg
Plating	12.12	mg	Supplier	Tin (Sn)	7440-31-5		12.12	mg
Wire Bond - Au	0.108	mg	Supplier	Gold (Au)	7440-57-5		0.108	mg